

特征 Features

- 齐纳击穿阻抗低; Low Zener Impedance
- 最大功率耗散 500mW; Power Dissipation of 500mW
- 高稳定性和可靠性。High Stability and High Reliability

机械数据 Mechanical Data

- 封装: SOD-123 封装 SOD-123 Small Outline Plastic Package
- 极性: 色环端为负极 Polarity: Color band denotes cathode end
- 环氧树脂 UL 易燃等级 Epoxy UL: 94V-0
- 安装位置: 任意 Mounting Position: Any

极限值和温度特性(TA = 25℃ 除非另有规定)

Maximum Ratings & Thermal Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified.)

参数 Parameters	符号 Symbol	数值 Value	单位 Unit
功率消耗 Power Dissipation	Pd	500 ¹⁾	mW
正向压降 Forward Voltage @IF=10mA	Vf	0.9 ²⁾	V
存储温度 Storage temperature range	Ts	-65-+150	℃

1) Device mounted on ceramic PCB: 7.6mm x 9.4mm x 0.87mm with pad areas 25mm²

2) Short duration test pulse used to minimize self-heating effect

3) f=1KHz

电特性 (TA = 25℃ 除非另有规定)

Electrical Characteristics (Ratings at 25℃ ambient temperature unless otherwise specified).

Type Number	Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 4)			Maximum Reverse Current	
		V _Z @I _{ZT}			I _{ZT}	Z _{ZT} @I _{ZT}	Z _{ZK} @I _{ZK}	I _{ZK}	I _R	V _R
		Nom(V)	Min(V)	Max(V)	mA	Ω		mA	uA	V
MMSZ5221C	2C1	2.4	2.35	2.45	20	30	1200	0.25	100	1.0
MMSZ5223C	2C3	2.7	2.65	2.75	20	30	1300	0.25	75	1.0
MMSZ5225C	2C5	3.0	2.94	3.06	20	30	1600	0.25	50	1.0
MMSZ5226C	2G1	3.3	3.23	3.37	20	28	1600	0.25	25	1.0
MMSZ5227C	2G2	3.6	3.53	3.67	20	24	1700	0.25	15	1.0
MMSZ5228C	2G3	3.9	3.82	3.98	20	23	1900	0.25	10	1.0
MMSZ5229C	2G4	4.3	4.21	4.39	20	22	2000	0.25	5	1.0
MMSZ5230C	2G5	4.7	4.61	4.79	20	19	1900	0.25	5	2.0
MMSZ5231C	2E1	5.1	5.00	5.20	20	17	1600	0.25	5	2.0
MMSZ5232C	2E2	5.6	5.49	5.71	20	11	1600	0.25	5	3.0
MMSZ5233C	2E3	6.0	5.88	6.12	20	7	1600	0.25	5	3.5
MMSZ5234C	2E4	6.2	6.08	6.32	20	7	1000	0.25	5	4.0
MMSZ5235C	2E5	6.8	6.66	6.94	20	5	750	0.25	3	5.0
MMSZ5236C	2F1	7.5	7.35	7.65	20	6	500	0.25	3	6.0

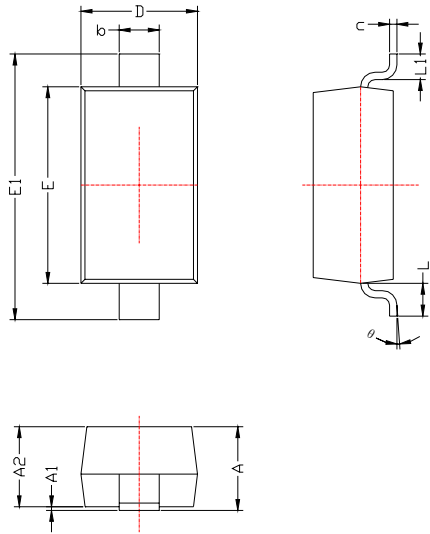
MMSZ5221C- MMSZ5259C Series

Type Number	Code	Zener Voltage Range (Note 2)				Maximum Zener Impedance (Note 4)			Maximum Reverse Current	
		$V_Z@I_{ZT}$			I_{ZT}	$Z_{ZT}@I_{ZT}$	$Z_{ZK}@I_{ZK}$	I_{ZK}	I_R	V_R
		Nom(V)	Min(V)	Max(V)	mA	Ω		mA	μA	V
MMSZ5237C	2F2	8.2	8.04	8.36	20	8	500	0.25	3	6.5
MMSZ5238C	2F3	8.7	8.53	8.87	20	8	600	0.25	3	6.5
MMSZ5239C	2F4	9.1	8.92	9.28	20	10	600	0.25	3	7.0
MMSZ5240C	2F5	10	9.80	10.20	20	17	600	0.25	3	8.0
MMSZ5241C	2H1	11	10.78	11.22	20	22	600	0.25	2.0	8.4
MMSZ5242C	2H2	12	11.76	12.24	20	30	600	0.25	1.0	9.1
MMSZ5243C	2H3	13	12.74	13.26	9.5	13	600	0.25	0.5	9.9
MMSZ5244C	2H4	14	13.72	14.28	9.0	15	600	0.25	0.1	10
MMSZ5245C	2H5	15	14.70	15.30	8.5	16	600	0.25	0.1	11
MMSZ5246C	2J1	16	15.68	16.32	7.8	17	600	0.25	0.1	12
MMSZ5248C	2J3	18	17.64	18.36	7.0	21	600	0.25	0.1	14
MMSZ5250C	2J5	20	19.60	20.40	6.2	25	600	0.25	0.1	15
MMSZ5251C	2K1	22	21.56	22.44	5.6	29	600	0.25	0.1	17
MMSZ5252C	2K2	24	23.52	24.48	5.2	33	600	0.25	0.1	18
MMSZ5253C	2K3	25	24.50	25.50	5.0	35	600	0.25	0.1	19
MMSZ5254C	2K4	27	26.46	27.54	5.0	41	600	0.25	0.1	21
MMSZ5255C	2K5	28	27.44	28.56	4.5	44	600	0.25	0.1	21
MMSZ5256C	2M1	30	29.40	30.60	4.2	49	600	0.25	0.1	23
MMSZ5257C	2M2	33	32.34	33.66	3.8	58	700	0.25	0.1	25
MMSZ5258C	2M3	36	35.28	36.72	3.4	70	700	0.25	0.1	27
MMSZ5259C	2M4	39	38.22	39.78	3.2	80	800	0.25	0.1	30

MMSZ5221C- MMSZ5259C Series

SOD-123 PACKAGE OUTLINE

Plastic surface mounted package

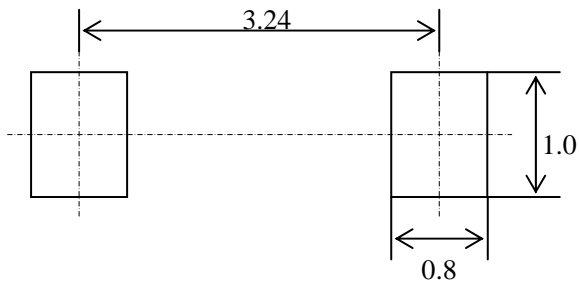


SYMBOL	DIMENSIONS	
	MIN.	MAX.
A	1.050	1.250
A1	0.000	0.100
A2	1.050	1.150
b	0.450	0.650
c	0.080	0.150
D	1.500	1.700
E	2.600	2.800
E1	3.550	3.850
L	0.500REF	
L1	0.250	0.450
θ	0°	8°

焊盘设计参考

Precautions: PCB Design

Recommended land dimensions for SOD-123 diode. Electrode patterns for PCBs



中心距: 3.24
脚宽: 0.55
焊盘宽: 1.00
脚长: 0.50
焊盘长: 0.80

技术要求:

- 1, 塑封体尺寸: 2.70 X 1.60
- 2: 未注公差为: ±0.05
- 3, 所有单位: mm